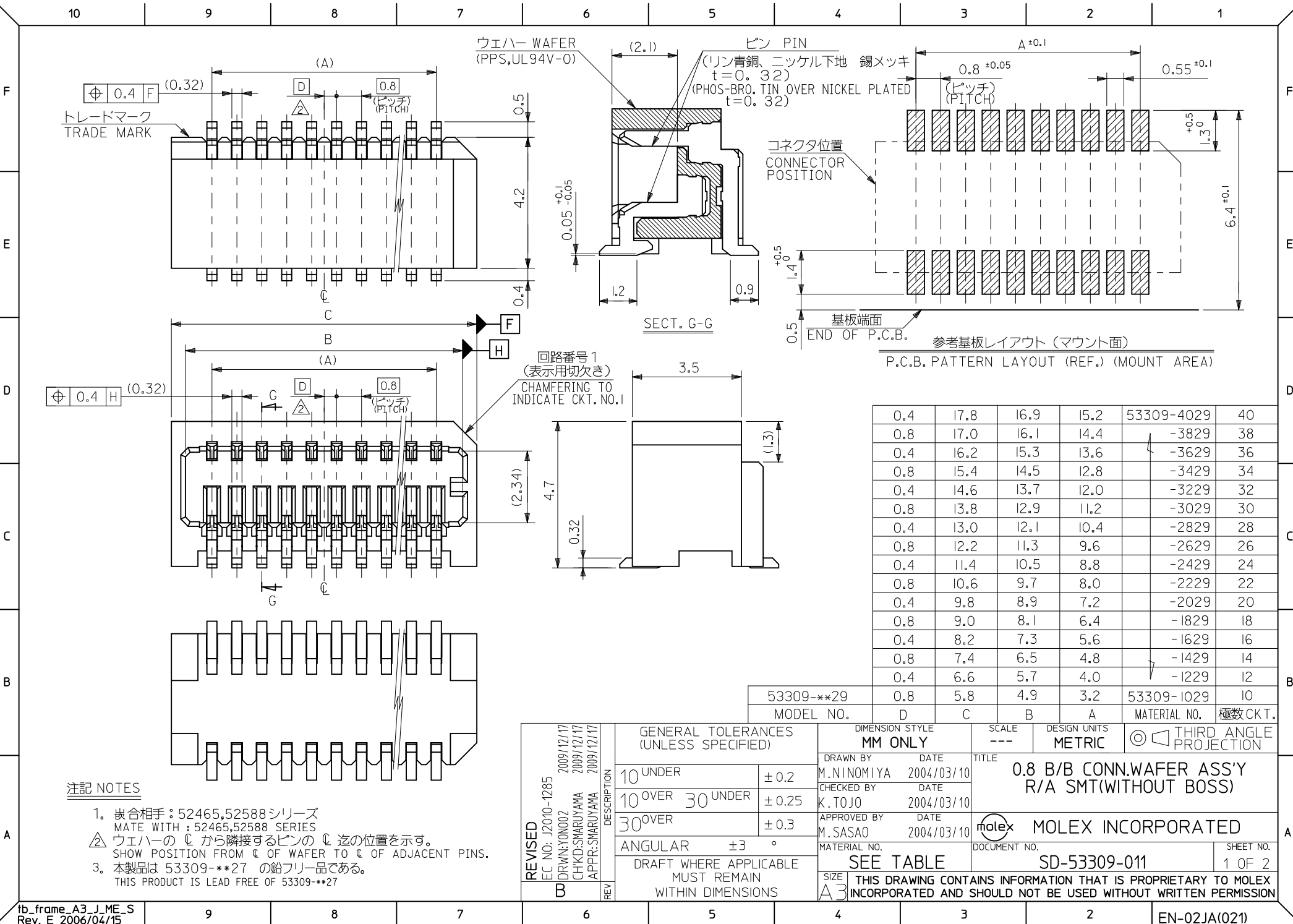




注記 NOTES

1. 嵌合相手: 52465,52588 シリーズ
MATE WITH : 52465,52588 SERIES
2. ウェハーの ② から隣接するピンの ② 迄の位置を示す。
SHOW POSITION FROM ② OF WAFER TO ② OF ADJACENT PINS.
3. 本製品は 53309-**27 の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 53309-**27

REVISED EC NO: J2010-1285 DRWN:YON002 CHKD:SMARUYAMA APPR:SMARUYAMA REV	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION			
		10 UNDER	± 0.2	DRAWN BY M.NINOMIYA	DATE 2004/03/10	TITLE 0.8 B/B CONN.WAFER ASS'Y R/A SMT(WITHOUT BOSS)					
		10 OVER 30 UNDER	± 0.25	CHECKED BY K. TOJO	DATE 2004/03/10						
		30 OVER	± 0.3	APPROVED BY M.SASAO	DATE 2004/03/10						
		ANGULAR ±3 °		MATERIAL NO.		MOLEX INCORPORATED		DOCUMENT NO.	SHEET NO.		
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		SD-53309-011		1 OF 2			
B	REV			SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						

10

9

8

7

6

5

4

3

2

1

F

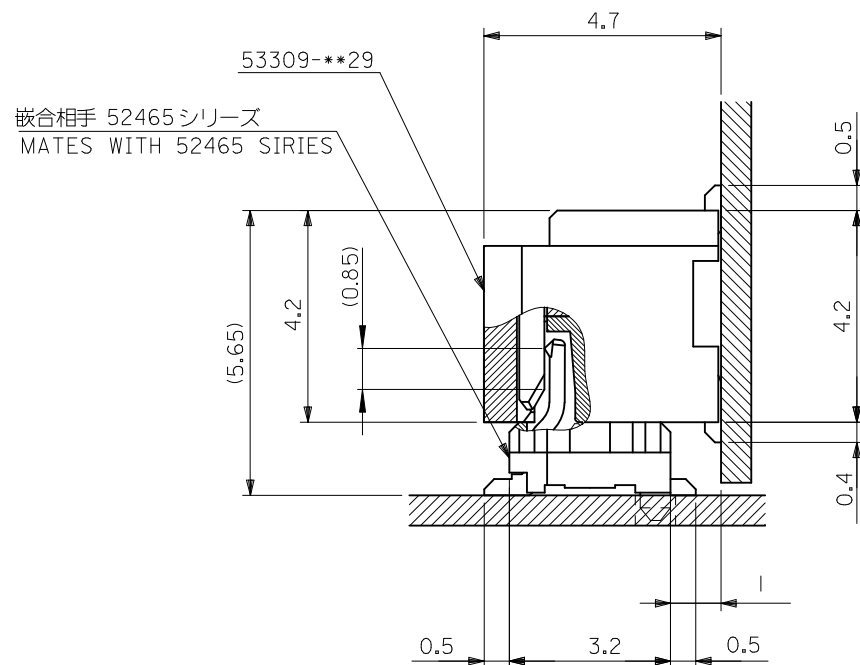
E

D

C

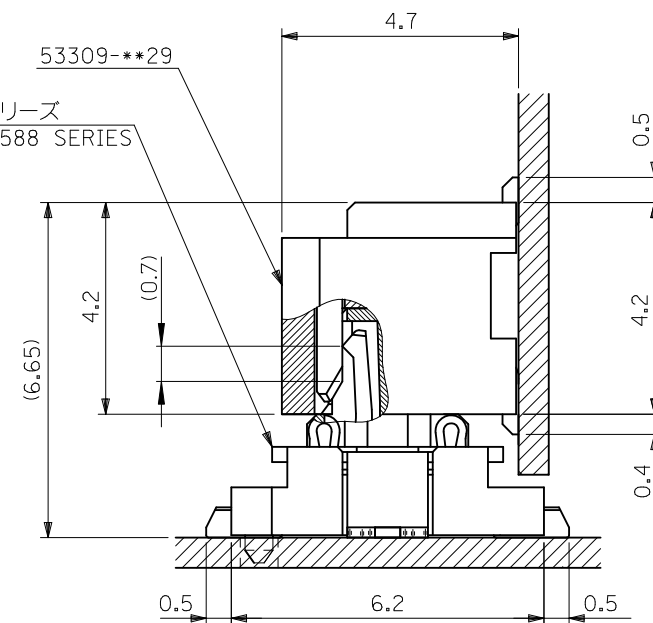
B

A



53309-***29
嵌合相手 52465 シリーズ
MATES WITH 52465 SERIES

嵌合状態図 (参考)
MATED DRAWING(REF.)



53309-***29
嵌合相手 52588 シリーズ
MATES WITH 52588 SERIES

嵌合状態図 (参考)
MATED DRAWING(REF.)

9

8

7

6

5

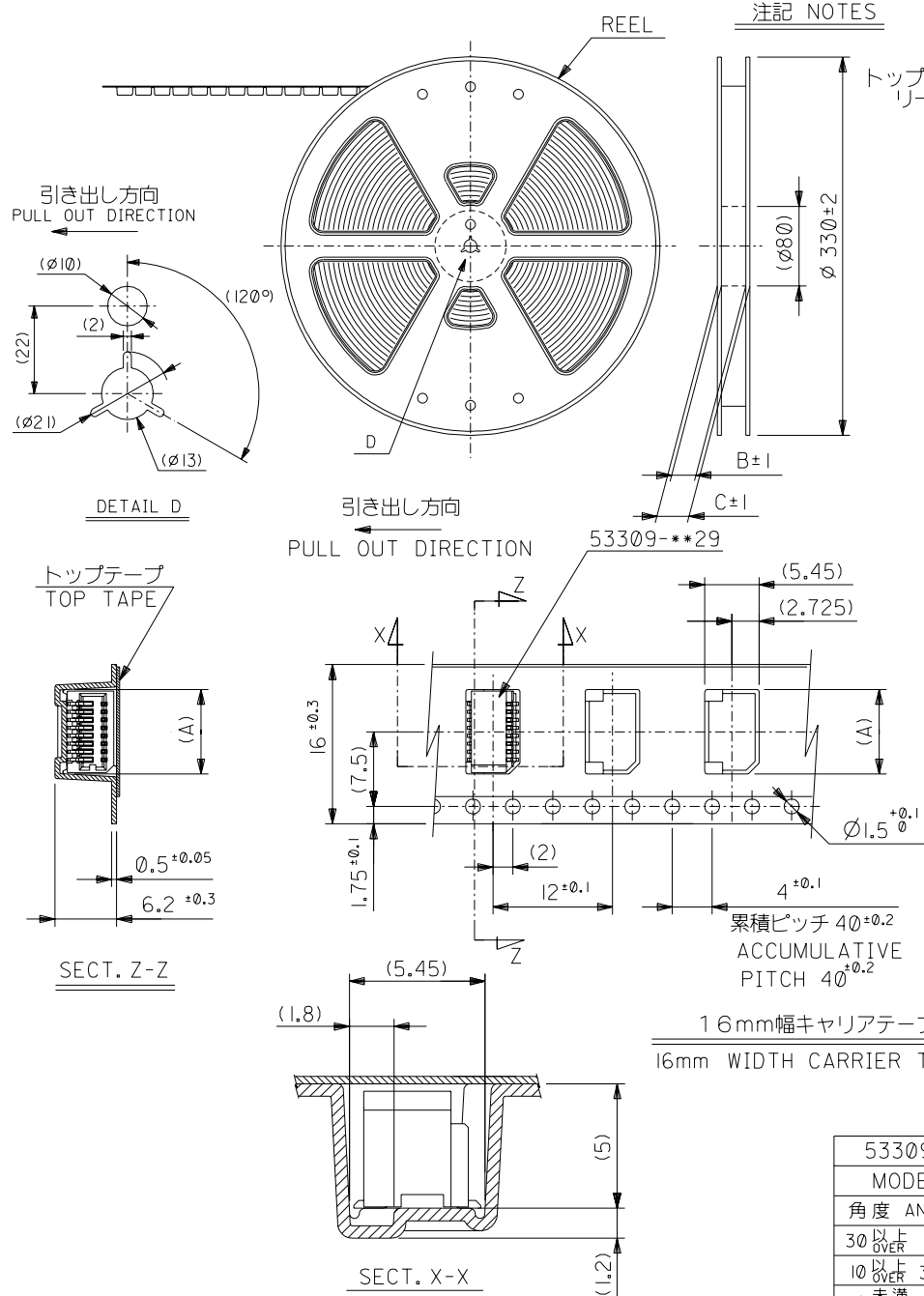
4

3

2

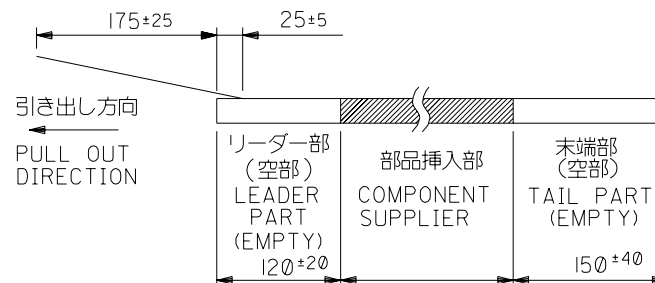
EN-02JA(021)

REVISED EC NO: J2010-1285 DRWN:YON002 CHKD:SMARUYAMA APPR:SMARUYAMA	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
		10 UNDER	± 0.2	DRAWN BY M.NINOMIYA	DATE 2004/03/10	TITLE 0.8 B/B CONN.WAFER ASS'Y R/A SMT(WITHOUT BOSS)		
		10 OVER 30 UNDER	± 0.25	CHECKED BY K.TOJO	DATE 2004/03/10			
		30 OVER	± 0.3	APPROVED BY M.SASAO	DATE 2004/03/10			
		ANGULAR ±3 °		MATERIAL NO. SEE SHEET 1		DOCUMENT NO. SD-53309-011	SHEET NO. 2 OF 2	
	REV	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			



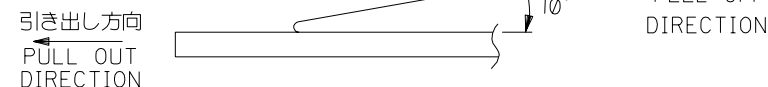
注記 NOTES

1. 梱包数量：1000個/リール NUMBER OF CONNECTORS:1000PCS/REEL
2. リードテープ長さ LEAD TAPE LENGTH
- トップテープ TOP TAPE
リーダー部 LEADER PART
未接着部 NON-BONDED PART



3. トップテープの剥離強度：(剥離方向は下図参照)
0.1N $\sim$ 1.3N(10gf $\sim$ 130gf) 尚、本規格値は、出荷時に適用。
(但し、輸送時に剥離が発生しない事。)

PEELING OFF FORCE OF TOP TAPE
0.1N $\sim$ 1.3N(10gf $\sim$ 130gf) (PEELING DIRECTION AS SHOWN IN FOLLOWING FIG.)
THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT
PEEL OFF SHOULD NOT BE ALLOWED,
DURING TRANSPORTATION



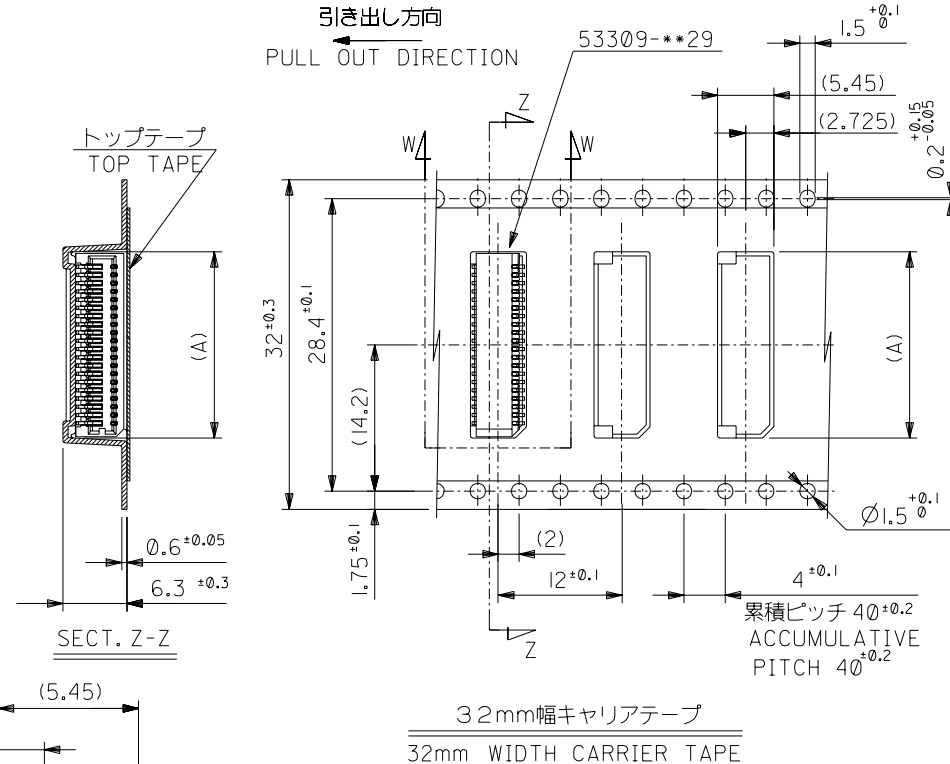
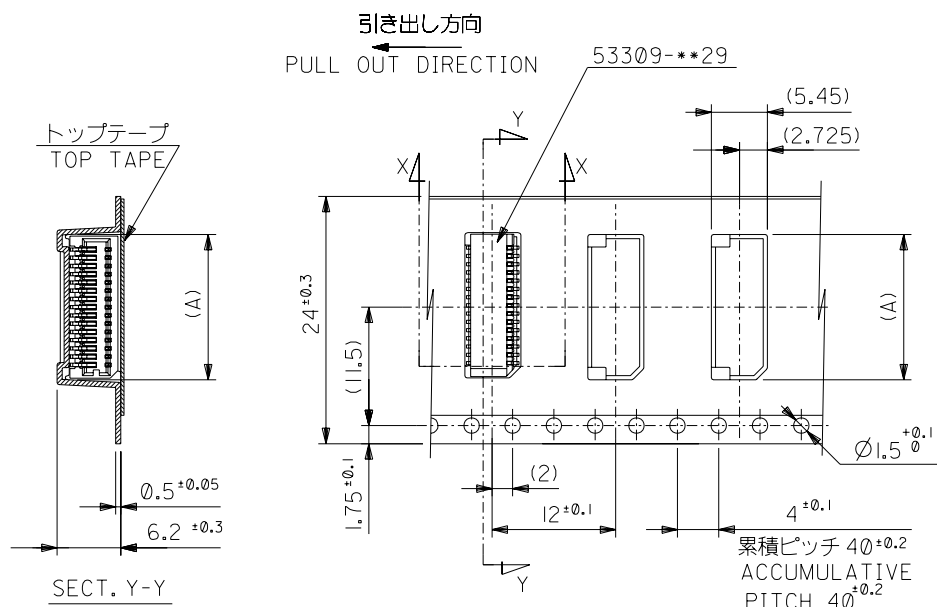
4. 材料
キャリアテープ：ポリプロピレン (PP)
トップテープ：PET, PE, PEF
リール：ポリスチレン (PS)
MATERIAL
<リサイクル材を含む>

CARRIER TAPE:POLYPROPYLENE
TOP TAPE:PET,PE,PEF
REEL:POLYSTYRENE(PS)
<RECYCLE MATERIAL CONTAINED>

5. 本製品は 53309-**91 の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 53309-**91.

16	21.4	17.4	9.3	53309-1870	18
			8.5	53309-1670	16
			7.7	53309-1470	14
			6.9	53309-1270	12
			6.1	53309-1070	10
キャリアテープ幅 CARRIER TAPE WIDTH	C	B	(A)	MATERIAL NO.	極数 CIRCUIT

53309-**70		材料 MATERIAL		注記参照 SEE NOTES		molex MOLEX-JAPAN CO.,LTD. 日本モレックス株式会社	
MODEL NO.		仕上げ FINISH		—		REVISE ONLY ON CAD SYSTEM	
角度 ANGLE		適用電線範囲 WIRE RANGE		—		TITLE 名称 0.8 BtB Conn Wafer Assy	
30 以上 OVER		被覆外径 INS. RANGE		—		RA SMT Without Boss	
10 以上 30 未満 OVER UNDER		DRAWN BY 04/03/10 M.NINOMIYA		CHK'D BY 04/03/10 K.TOJO		Embstp Pkg	
10 未満 UNDER		0 新規作成 (J2004-2995) RELEASED		M.N. K.		-LEAD FREE-	
一般公差 GENERAL TOLERANCES		記号 LTR		変更内容 REVISION RECORD		DR. CHK. DATE	
						APP'D BY 04/03/10 M.SASAO	
						尺度 SCALE	
						—	
						DWG. NO. (SHEET 1 OF 2)	
						SD-53309-012	
						REV	
						0	



24	29.4	25.4	16.5	53309-3670	36
			15.7	53309-3470	34
			14.9	53309-3270	32
			14.1	53309-3070	30
			13.3	53309-2870	28
			12.5	53309-2670	26
			11.7	53309-2470	24
			10.9	53309-2270	22
キャリアテープ幅 CARRIER TAPE WIDTH	C	B	10.1	53309-2070	20
			(A)	MATERIAL NO.	極数 CIRCUIT

						材料 MATERIAL		molex MOLEX-JAPAN CO.,LTD. 日本モレックス株式会社	
53309-***70						SHEET 1 OF 2参照 REFER TO SHEET 1 OF 2			
MODEL NO.						仕上げ FINISH		REVISE ONLY ON CAD SYSTEM	
角度 ANGLE		±3°				適用電線範囲 WIRE RANGE		TITLE 名称	
30 以上 OVER		±0.3				被覆外径 INS. RANGE		0.8 BtB Wafer Assy RA SMT Without Boss Embstp Pkg	
10 以上 30 未満 OVER UNDER		±0.25						-LEAD FREE-	
10 未満 UNDER		±0.2		0 新規作成 (J2004-2995)		M.N. K.T. 04/03/10		DWG. NO. (SHEET 2 OF 2) REV	
GENERAL TOLERANCES		記号 TR		変更内容 REVISION RECORD		DR. CHK. 日付 DATE		SCALE	
						APP'D BY 04/03/10 M.SASAO		SD-53309-012 0	